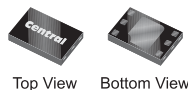
Material Composition Specification

TLM621H Case



Top View Bottom View

Device average mass . . . . 3.77 mg

Fluctuation margin . . . . +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	6.63%	0.25	Si	7440-21-3	6.63%	0.25	66,278
bond wire	gold	0.53%	0.02	Au	7440-57-5	0.53%	0.02	5,302
leadframe	Cu alloy	43.21%	1.63	Cu	7440-50-8	41.89%	1.58	418,876
				Ni	7440-02-0	1.01%	0.038	10,074
				Si	7440-21-3	0.27%	0.01	2,651
				Mg	7439-95-4	0.05%	0.002	530
die attach	silver epoxy	2.65%	0.1	Ag	7440-22-4	1.86%	0.07	18,558
				epoxy resin	Proprietary	0.8%	0.03	7,953
encapsulation*	EMC GREEN	46.39%	1.75	silica (fused)	60676-86-0	43.48%	1.64	434,783
				epoxy resin	29690-82-2	1.33%	0.05	13,256
				phenol resin	9003-35-4	1.33%	0.05	13,256
				carbon black	1333-86-4	0.27%	0.01	2,651
plating	Ni/Pd/Au Process	0.58%	0.022	Ni	7440-02-0	0.5%	0.019	5,037
				Pd	7440-05-3	0.05%	0.002	530
				Au	7440-57-5	0.03%	0.001	265

*EMC GREEN molding compound is Halogen-Free.

Disclaimer
The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.